

## Fairchild Semiconductor Product Package Material Disclosure

| Package Type                | DO-41  |                 |  |                             |                             |   |
|-----------------------------|--|-----------------|--|-----------------------------|-----------------------------|---|
| Weight of Package (grams)   | Maximum  | 0.271           |  |                             |                             |   |
|                             | Minimum  | 0.285           |  |                             |                             |   |
| Component                   | Material   | Weight in grams | Substance in material  | Wt% in finished product min | Wt% in finished product max | CAS#  |
| <b>Studleads CCS Wire</b>   | Fe, Cu cladded   | 0.178-0.180     | Fe/Cu Alloy  | 63.9%                       | 64.6%                       | 7439-89-6/<br>7440-50-8                             |
| <b>Studleads Dumet Wire</b> | Fe /Ni/ Cu Alloy(Trace Element)  | 0.036-0.038     | Fe /Ni/ Cu Alloy(Trace Element)  | 12.93%                      | 13.64%                      | 7439-89-6/<br>7440-02-0/<br>7440-50-8               |
| <b>Glass Sleeves</b>        | PbO/ SiO <sub>2</sub> / K <sub>2</sub> O/ B <sub>2</sub> O <sub>3</sub> Alloy(Trace Element) | 0.050-0.060     | PbO/ SiO <sub>2</sub> / K <sub>2</sub> O/ B <sub>2</sub> O <sub>3</sub> Alloy(Trace Element) | 17.95%                      | 21.54%                      | 1317-36-8/<br>7631-86-9/<br>12136-45-7<br>1303-86-2 |
| <b>Plating</b>              | Pure Tin   | 0.0070-0.0072   | Sn   | 2.51%                       | 2.59%                       | 7440-31-5   |
| <b>Marking Ink</b>          | Carbon Black/ Formaldehyde /Phenol/ Triethylene glycol monomethyl ether                      | 0.000006        | Carbon Black/ Formaldehyde /Phenol/ Triethylene glycol/ monomethyl ether                     | 0.022%                      | 0.022%                      | 7440-44-0/<br>50-00-0/<br>108-95-2/<br>112-35-6     |



### Materials Disclosure Disclaimer

The information provided in this Materials Disclosure is, to our knowledge, correct. However, there is no guarantee of completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in this statement regarding the minute amounts of dopant and metal materials contained within the electrically active or passive devices contained within the finished product.